

PRSA-L300-Fxx-Si-PCB/CHP

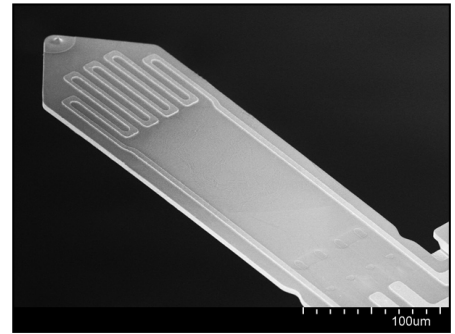
Silicon piezo-resistive sensing cantilevers

xx...50/60/80

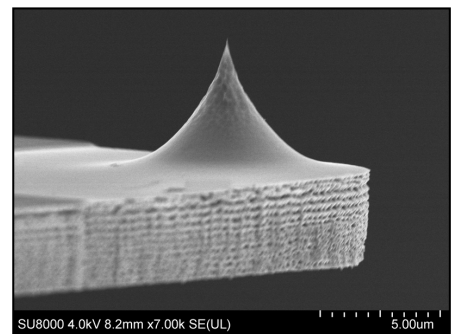


General description

Piezo-Resistive Sensing Active (PRSA) probes are silicon cantilevers with on chip integrated piezo-resistors and a heater for self-sensing and self-actuating scanning probe microscopy applications. The piezo-resistors are integrated into a matched Wheatstone bridge to raise the sensitivity and compensate environmental thermal drift. By using the self-sensing readout no laser adjustment is necessary in comparison to conventional optical readout AFM systems. This saves time during a cantilever change. The free space above the cantilever enables new applications and combination of AFM with various instruments. The cantilever chip is bonded to a small printed circuit board (PCB) with a small connector for a quick cantilever change. The counter part PCB for the cantilever PCB can be connected to a low-noise pre-amplifier with a flat flex cable.



Tip side of a PRSA-L300 cantilever with Al tracks for reading out the sensor signal



Side view of a PRSA-L300 cantilever

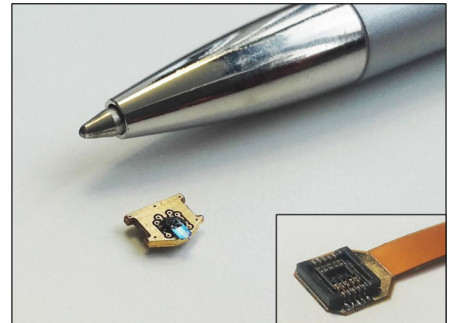
Specifications

Model **	PRSA-L300-F60-Si-CHP	
	PRSA-L300-F50-Si-PCB	PRSA-L300-F80-Si-PCB
Tip radius (apex)	<15 nm	
Tip height	4...6 µm	
Tip material	silicon	
Resonant frequency **	30..65 kHz	65...95 kHz
Spring constant **	1...15 N/m	15...56 N/m
AFM mode	contact, non-contact	non-contact
sensitivity*	1...2 µV/nm	
force sensitivity*	0.5...56 nN/µV	
Length, width	300 ±5 µm, 110 ±3 µm	
Material	silicon cantilever, boron doped 1k Ohm piezo resistors, aluminium tracks	
Deflection sensing	on chip piezo-resistive bridge	
Actuator	external shaker or on chip heater (20-45 Ohm)	
Electrical connections	bonded to small PCB with connector (counter part PCB available) or optional bonding pads on chip	
Chip dimensions (h, w, l)	0.3 / 1.2 / 2.5 mm	
* not amplified (signal direct at the chip), 2.048 V bridge supply		
** Cantilever models are divided in two parameter ranges when electrical characterization is possible with bonded cantilevers		

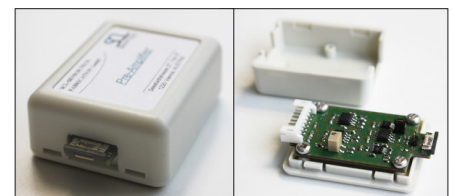
Applications:

- Integration on a standard AFM scanner and high-speed AFM
- Force or deflection measurements within TEM, SEM, XPS, etc.

What about your application? Contact us!



Cantilever is bonded to a 6 x 4.5 mm PCB (height with connector 1.6 mm, complete height connected to CP-PCB: 1.8 mm); right: counter part PCB



Hardware for amplified readout:
Low-noise pre-amplifier (45x35 mm)

SCL-Sensor.Tech. Fabrication GmbH

Visit our website www.sclsensortech.com and contact our sales experts!

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